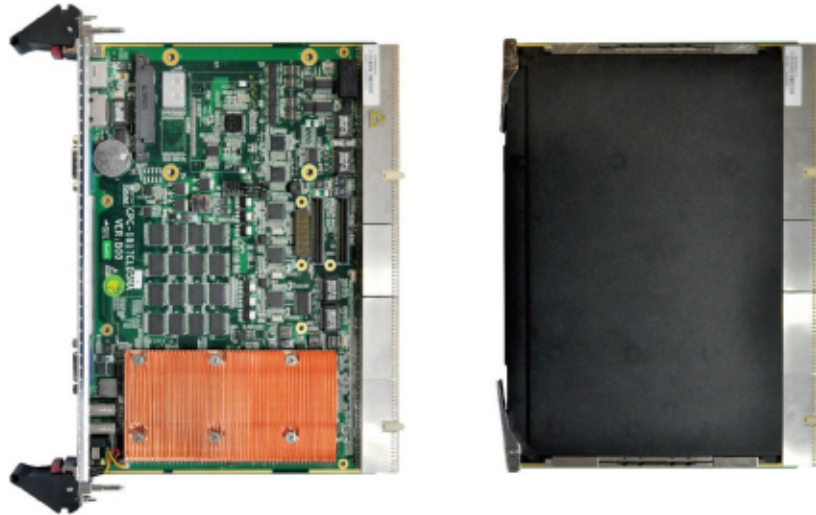


CPC-1817

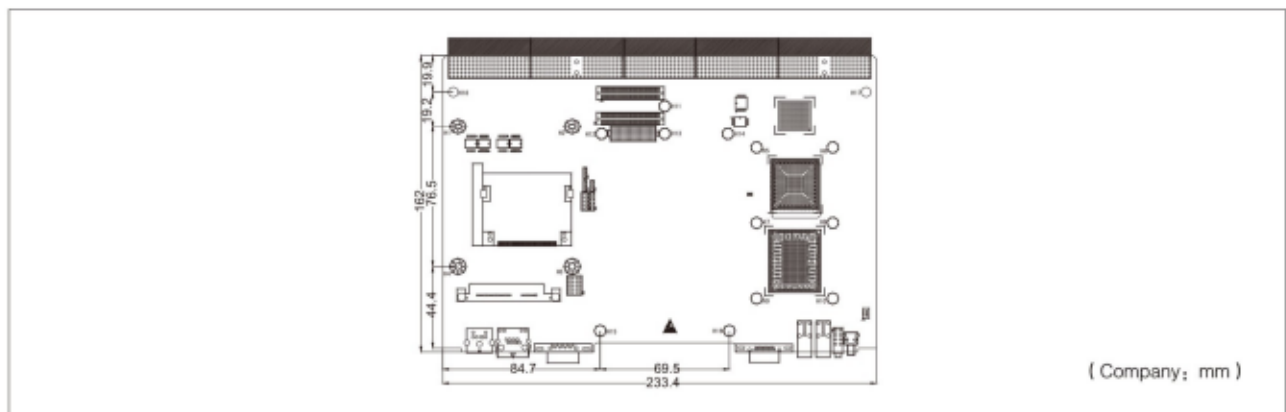
6U Compact PCI Intel® i7 Blade



Features:

- ◆ Supports air-cooled or rugged conduction-cooled
- ◆ Onboard 32nm intel® Core™ i7 mobile processor
- ◆ Up to 8GB soldered DDR3 1066 ECC memory
- ◆ 1*33MHz/32bit PMC site, 1*PCI-E x8 XMC site
- ◆ Supports up to 5*GbE LAN, two for PICMG 2.16 packet switching
- ◆ Supports onboard SATA drive, CF card and soldered 8GB NAND Flash
- ◆ Supports 2*isolated RS232/422/485 port, up to 2.5kV
- ◆ Available rear I/O board: CPC-RP807

Product size chart



Specifications

Compact PCI BUS	J1/J2 support 32Bit、33/66MHz CPCI BUS
	Compatible PICMG 2.0 specification PICMG 2.1 hot swap specification 3.3V/5V VIO signal environment
	Expand CPCI BUS by PCI-E x16 to PCI bridge
CPU	CPC-1817CLD5NA-H: i7-610E 2.53GHz, BGA, 4MB Smart Cache, 35W TDP CPC-1817CLD5NA: i7-620LE 2.0GHz, BGA, 4MB Smart Cache, 25W TDP CPC-1817-MIL: i7-620UE 1.06GHz, BGA, 4MB Smart Cache, 18W TDP Mobile Intel® QM57 Express Chipset
Memory	Onboard 4G DDR III ECC SDRAM 800/1066MHz memory
Display	Support DVI-I+DVI-D dual-display, VGA, LVDS Front : VGA; 2048x1536@60Hz Rear: DVI-D, DVI-I support dual-display up-down and left-right extended display mode, single display support1600x1200 (60Hz) Rear LVDS (18bit) share PINs with DVI-D
Storage	Front I/O: Onboard 8GB SSD CPC-1817CLD5NA: 1*2.5" SATA HDD; CPC-1817CLD5NA-MIL: 1*CF slot Rear I/O: 2*SATA
PMC/XMC	1*32bit, 33MHz 3.3V/5V PMC site 1*XMC SITE via PCI-E x8 bus
LAN	Rear I/O: 2*GbE 2*redundant GbE provide PICMG2.16 function to rear board
Front I/O	CF slot
Rear I/O	CPC-RP807; USB2.0x2、DB9 type RS232/422/485switchable, Y type PS/2, DVI-D, DVI-I, 2*GbE, MIC-IN/LAN-IN/LINE-OUT
System detection	WINBOND W83627DHG build-in watchdog timer, support 1-255 sec/min timer system reset or interrupt Monitors system voltage, current and temperature
Mechanical specification	Dimension : 6U 4HP CompactPCI 233mm(L)x160mm(W) Shock:□30g, 11ms (operating)50g, 11ms (non-operating) Vibration (5Hz-500MHz):1.5g(operating)2.0g(non-operating) Salt-Fog test: 2g/m³according to GJB150.11A-2009 Mould test: Satisfy Class One according to GJB150.10A-2009 Wet-Hot test: No corrosion for metal component under 100% humidity; 40°C ± 2°C, Humidity 90% ± 3, normal storage and work Oil-Fog test: 40mg/m³, normal storage and work
Compliant specifications	PICMG 2.0 R 3.0 CompactPCI Specification PICMG 2.1 R 2.0 CompactPCI Hot Swap Specification PICMG 2.16 R 1.0 Packet Switching Backplane Specification
OS	Windows XP、Linux、Vxworks

Ordering Information

Part Number	Model Number	Description
0030-018031	CPC-1817CLD5NA-H/Tri-proof	6U CompactPCI motherboard/i7-610E 2053GHz CPU,BGA/QM57 Express Chipset/VGA/Dual DVI (Rear)/Onboard 4GB DDR III ECC Memory/GbE/COM/2*USB/SATA HDD bay/Onboard 8GB SSD/PMC/XMC/-10-55°C
0030-018171	CPC-1817CLD5NA-MIL/Tri-proof	6U CompactPCI Rugged conductive motherboard/i7-620UE 1.06GHz BGA CPU/QM57 Express Chipset/CF slot/Dual DVI (Rear)/Onboard 4GB DDR III Memory/Onboard 8GB SSD/-40-80°C wide temperature
0060-004731	CPC-RP807/Tri-proof	CPC-1817CL5NDA Rear IO board/DVI-I/DVI-D/ Onboard LVDS optional/COM/2*USB/2*GbE/Line-out/line-in/Mic-in/Onboard COM port pin/2*SATA